

Fig. 1A

Fig. 1B

Fig. 1C

STEP1~3

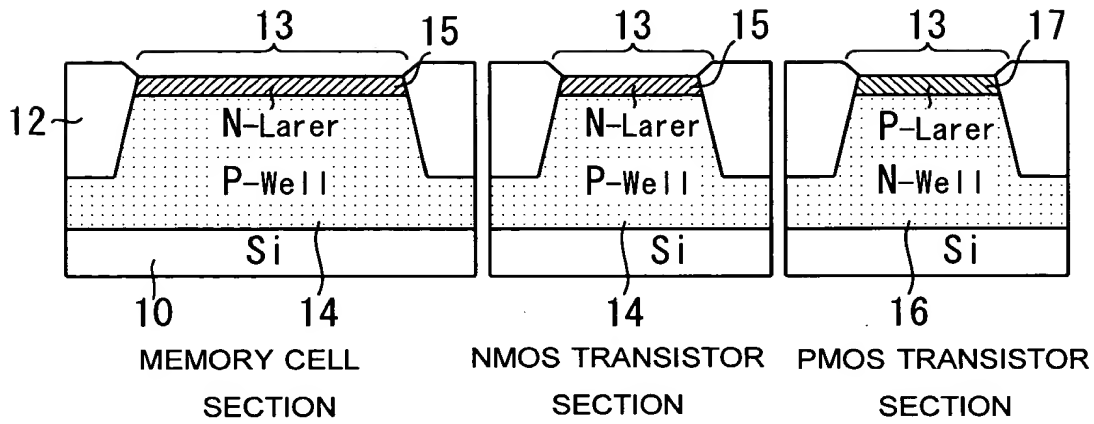
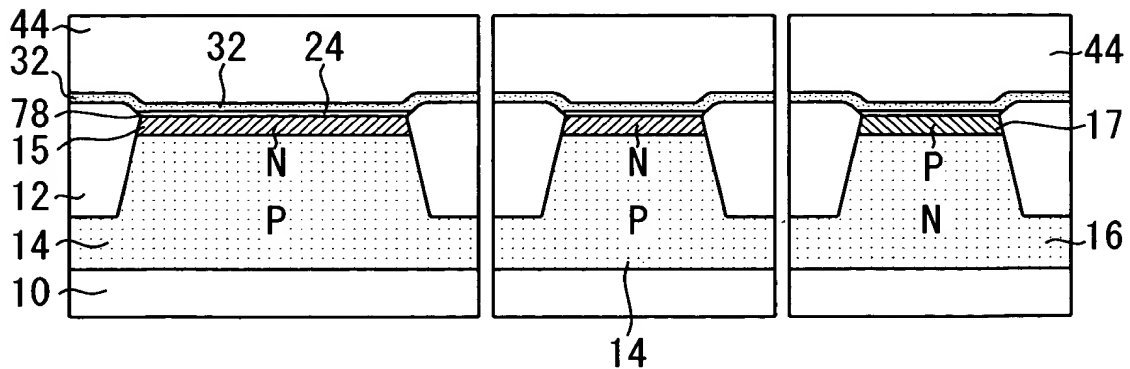


Fig. 2A

Fig. 2B

Fig., 2C

STEP4, 5



09766846-012301

Fig. 3A

Fig. 3B

Fig. 3C

STEP6

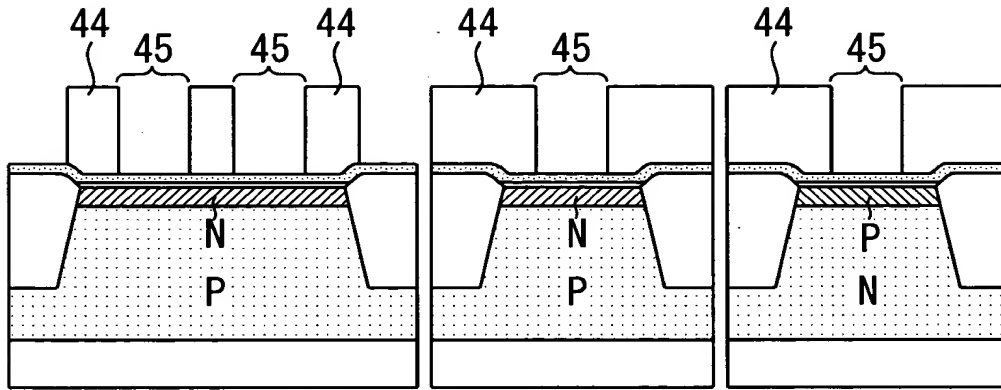


Fig. 4A

Fig. 4B

Fig. 4C

STEP7

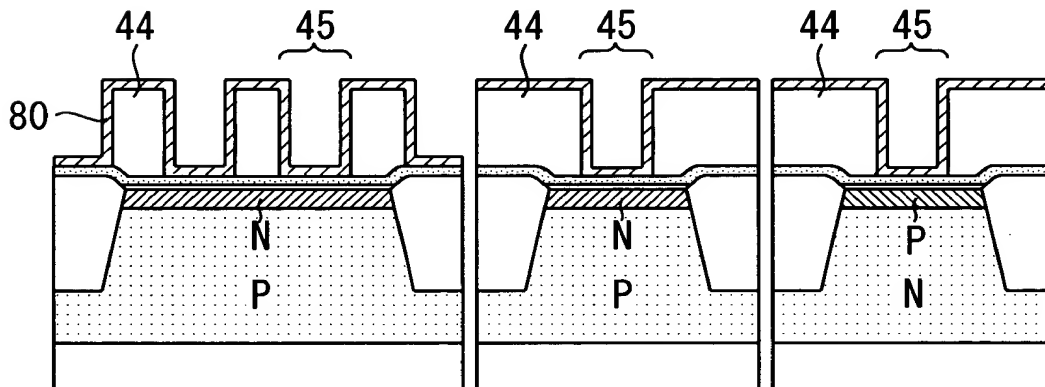


Fig. 5A

Fig. 5B

Fig. 5C

STEP8

STEP9

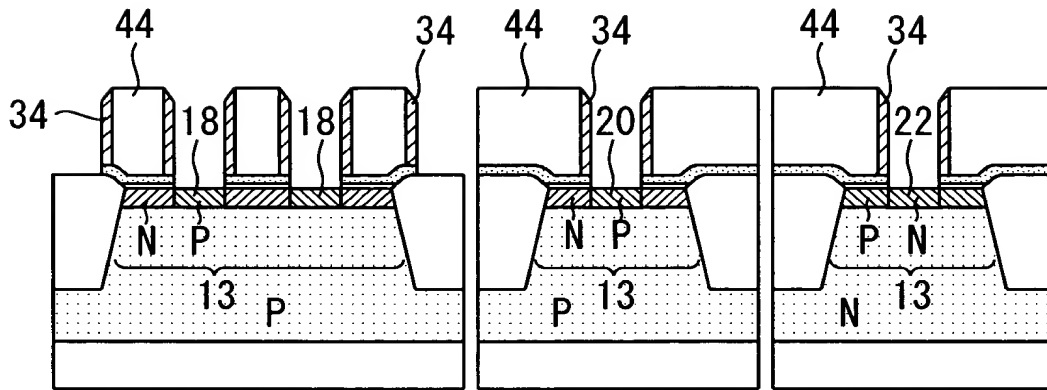
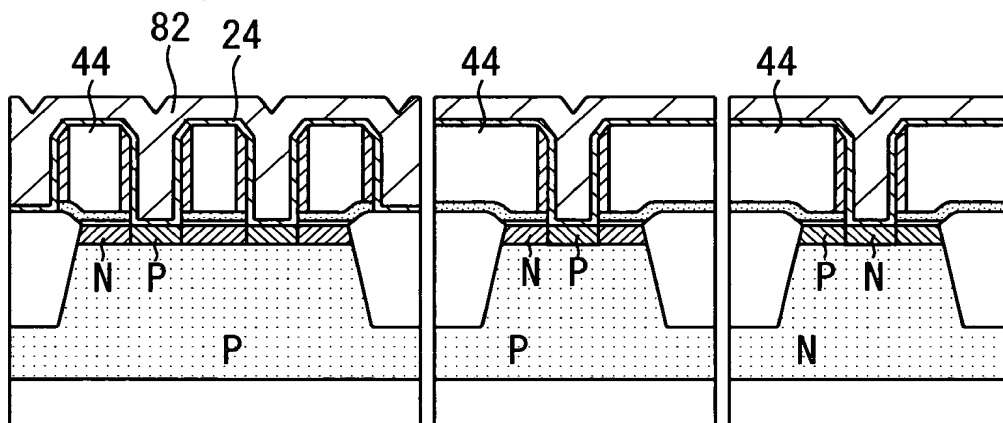


Fig. 6A

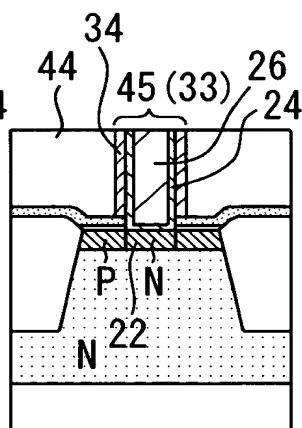
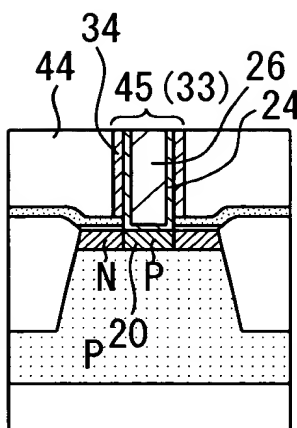
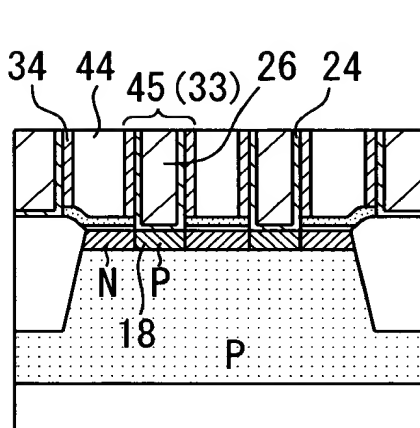
Fig. 6B

Fig. 6C

STEP10



## STEP 11



## STEP12

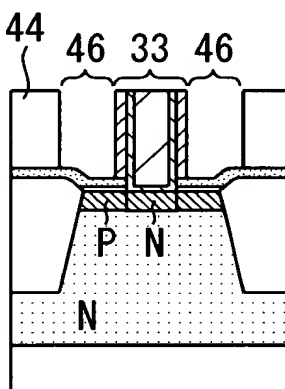
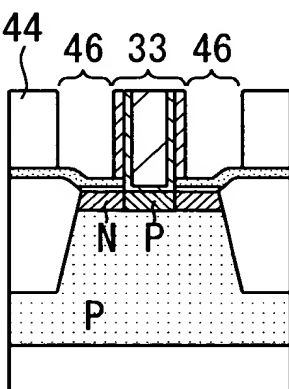
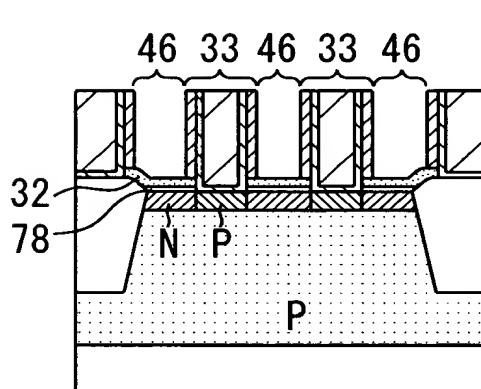


Fig. 9A

Fig. 9B

Fig. 9C

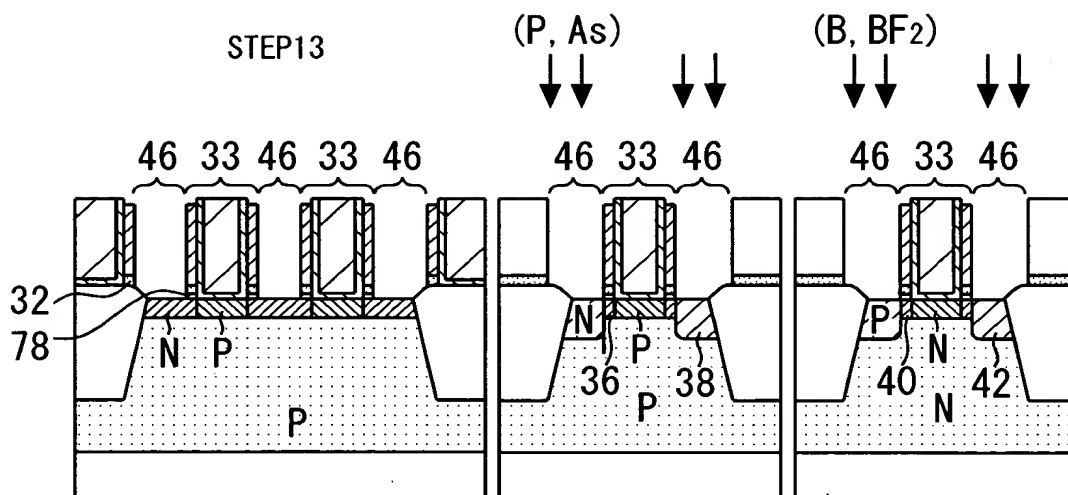


Fig. 10A

Fig. 10B

Fig. 10C

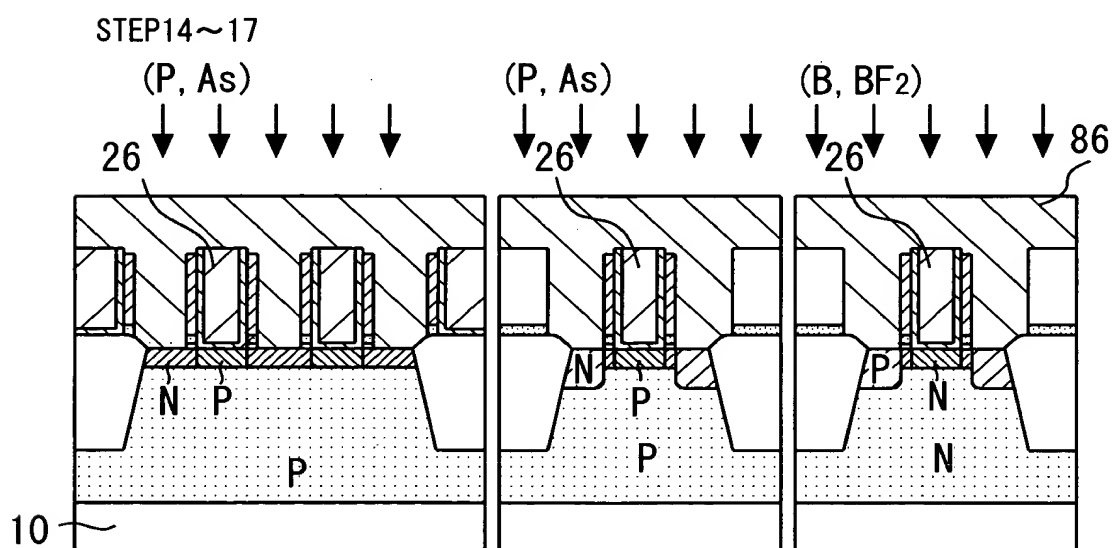


Fig. 11A

Fig. 11B

Fig. 11C

STEP18

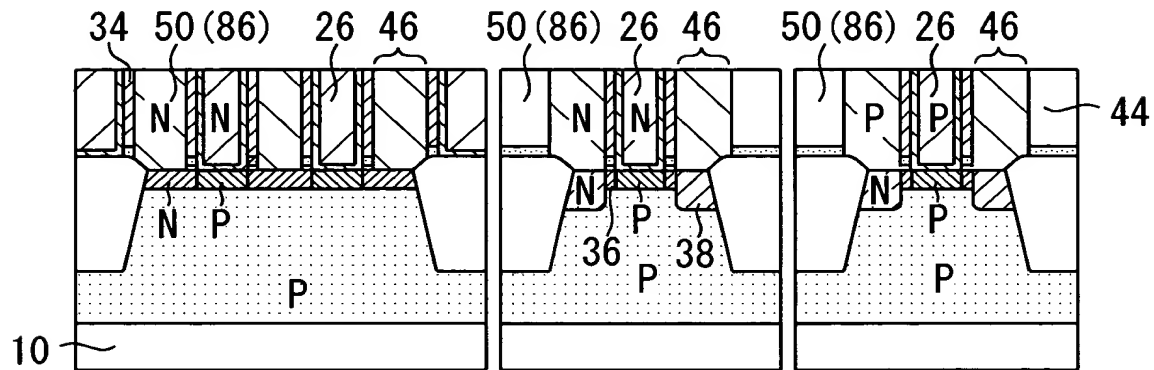
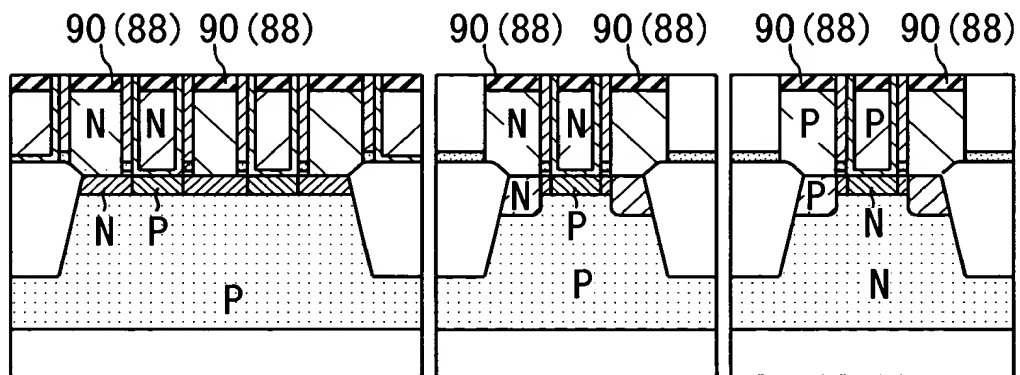


Fig. 12A

Fig. 12B

Fig. 12C

STEP19~21



(a)

(b)

(c)

**Fig. 13C**

Figure 1 shows three cross-sectional views of a semiconductor device during fabrication. The substrate is P-type. In (a), layers 50, 33, 54, 92, and 60(94) are shown. In (b), additional layers 50, 54, and 92 are added. In (c), further layers 50, 54, and 92 are added, and a top layer 52 is present.

**Fig. 14C**

Fig. 15A

Fig. 15B

Fig. 15C

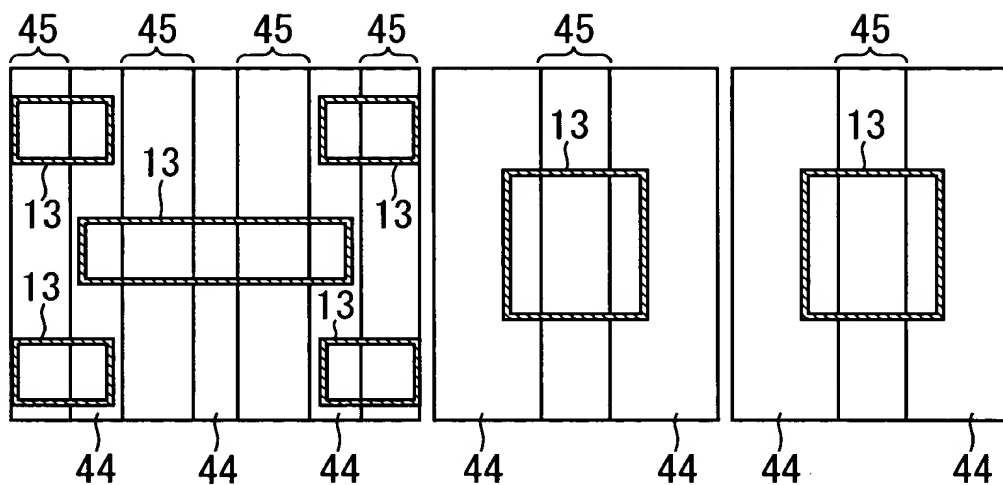


Fig. 16A

Fig. 16B

Fig. 16C

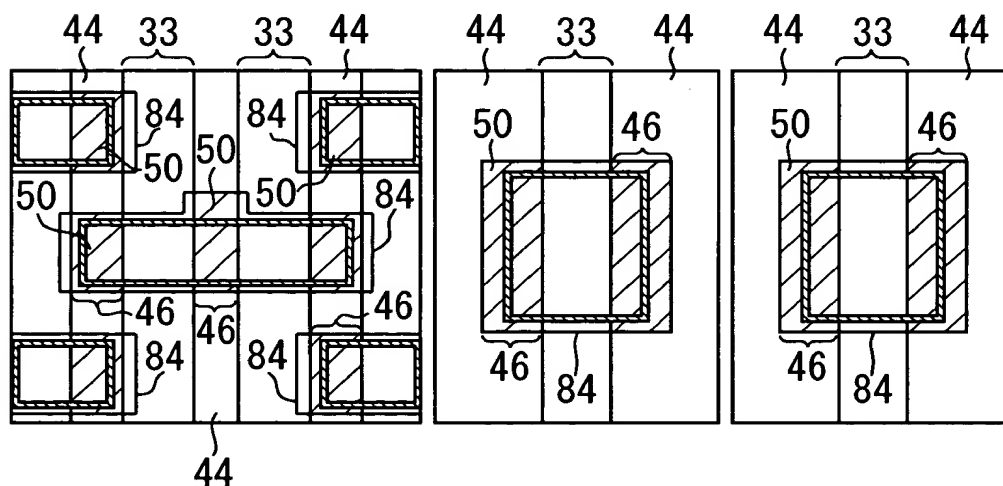




Fig. 17A

Fig. 17B

Fig. 17C

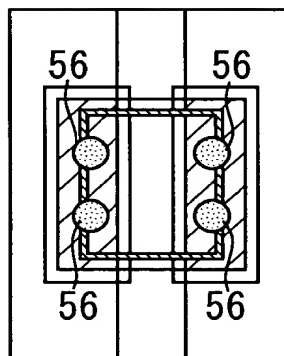
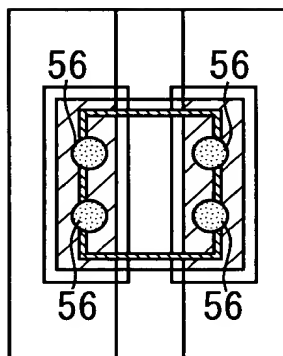
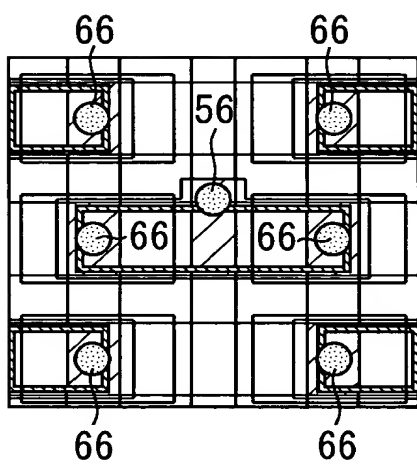


Fig. 18A

Fig. 18B

Fig. 18C

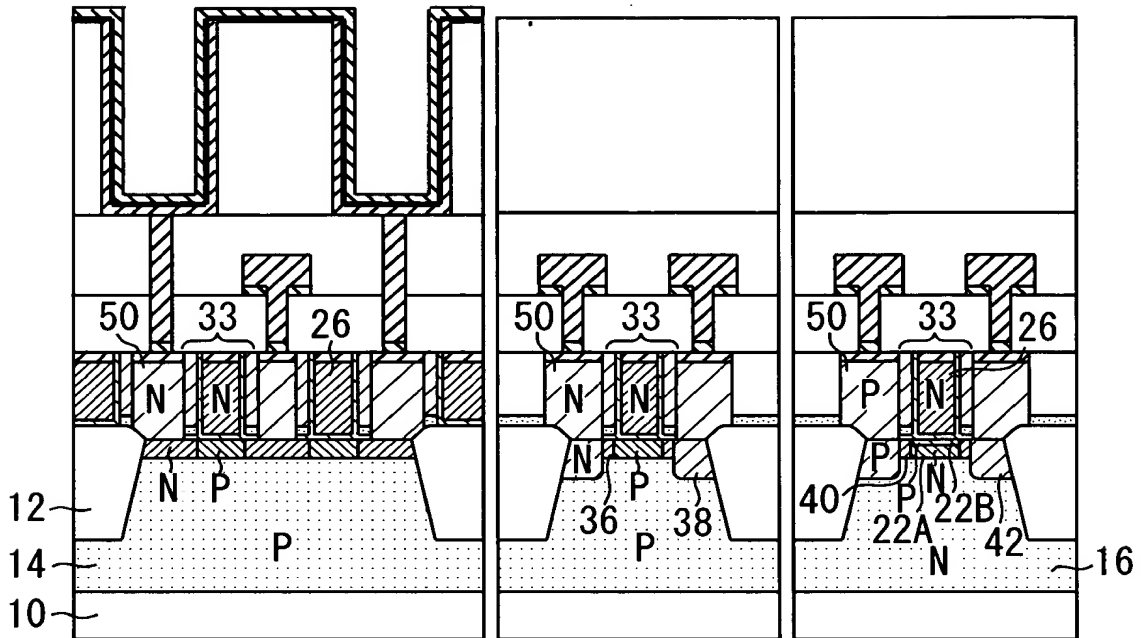


Fig. 19A

Fig. 19B

Fig. 19C

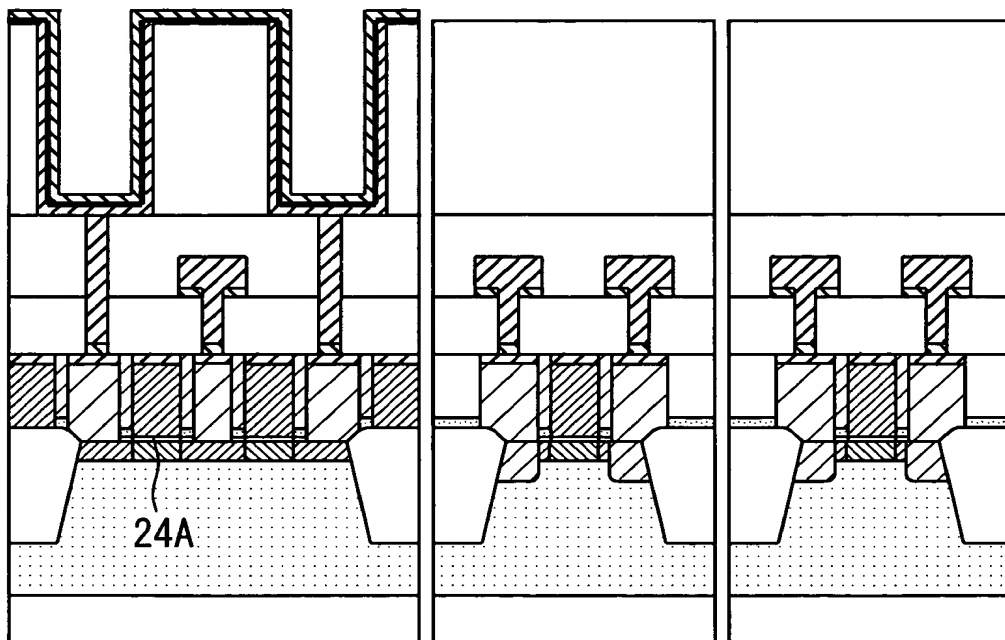


Fig. 20A

Fig. 20B

Fig. 20C

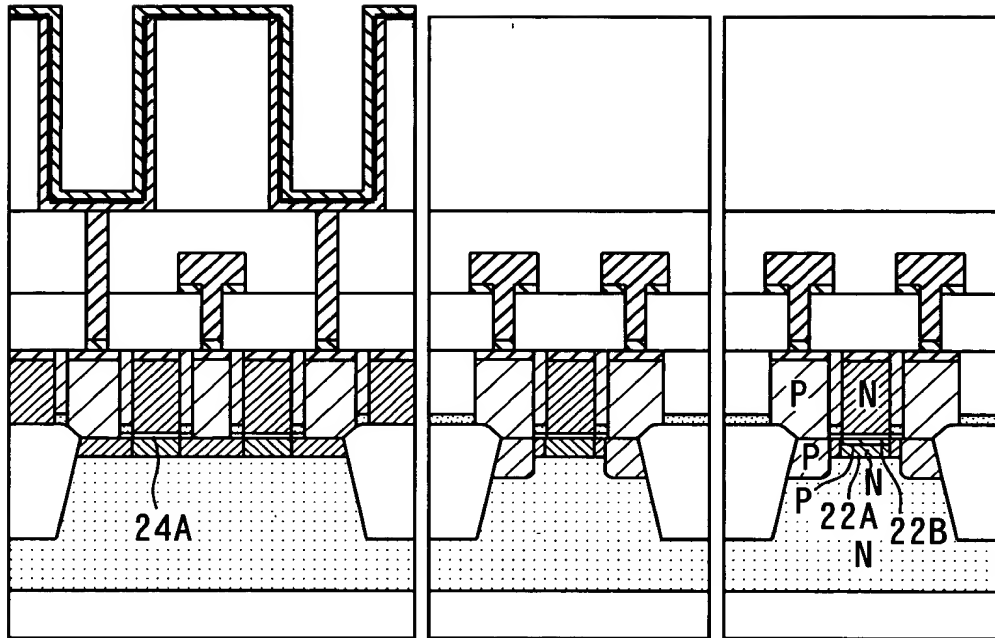


Fig. 21A

Fig. 21B

Fig. 21C

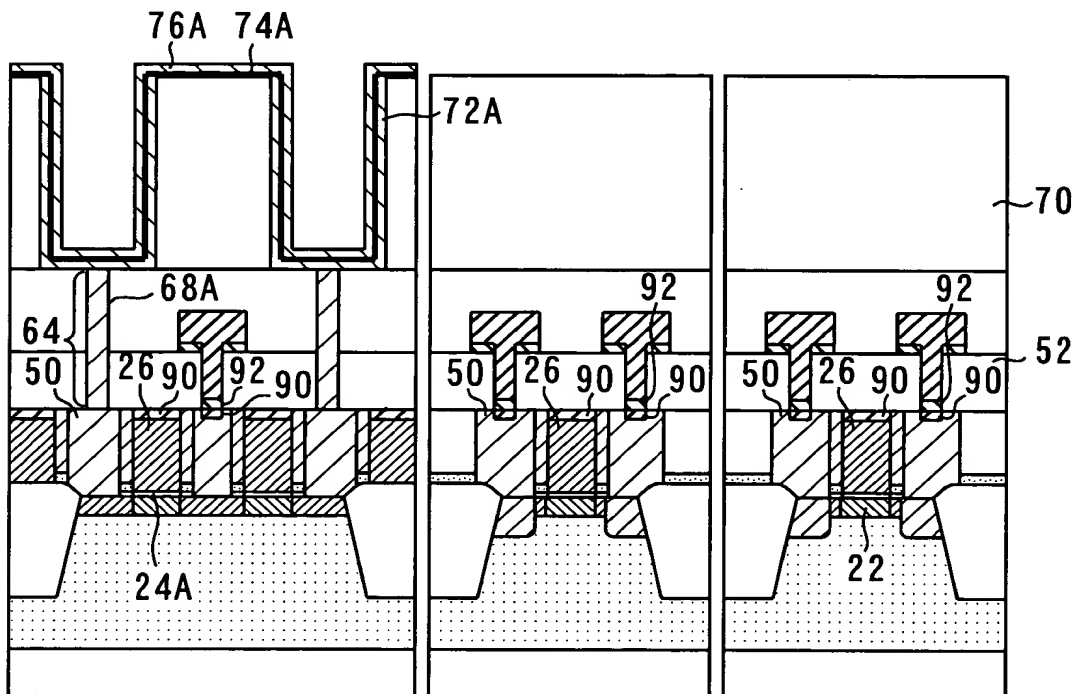


Fig. 22A

Fig. 22B

Fig. 22C

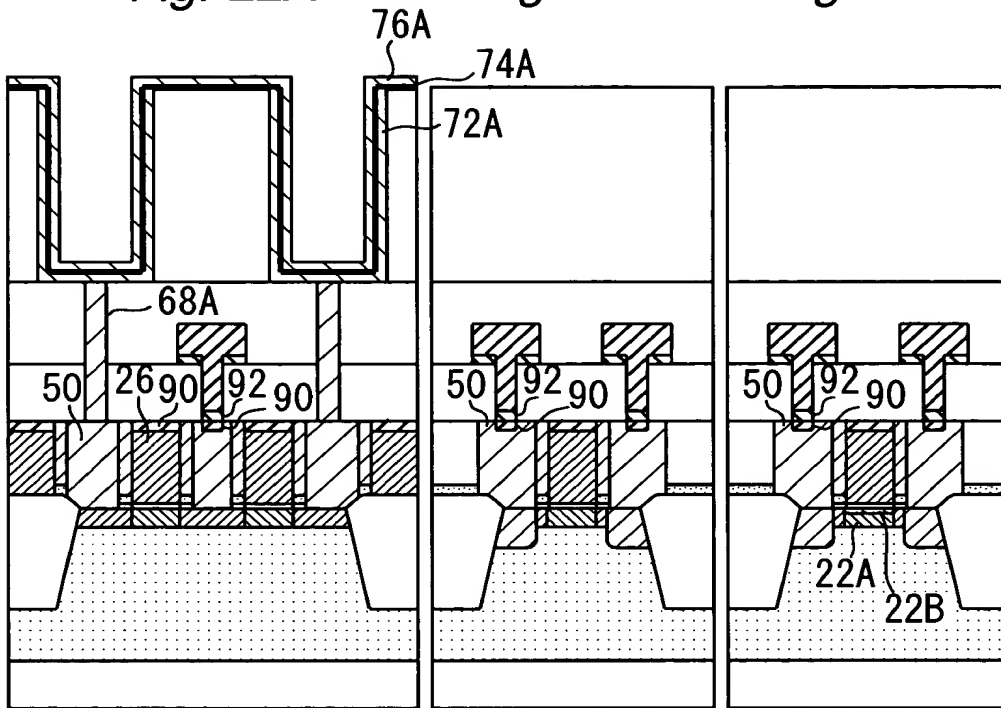


Fig. 23A

Fig. 23B

Fig. 23C

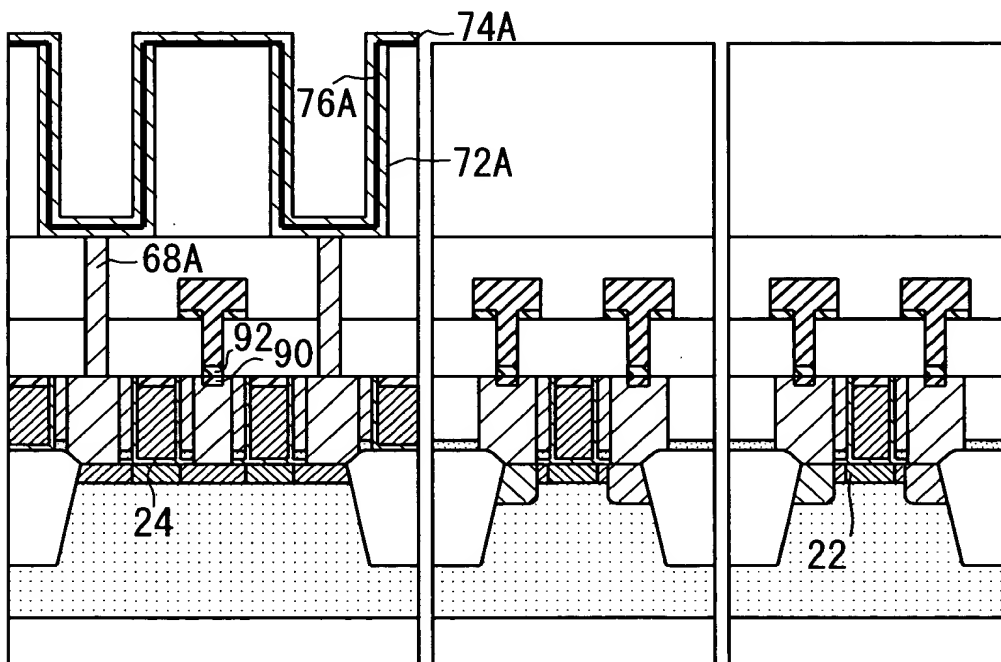


Fig. 24A

Fig. 24B

Fig. 24C

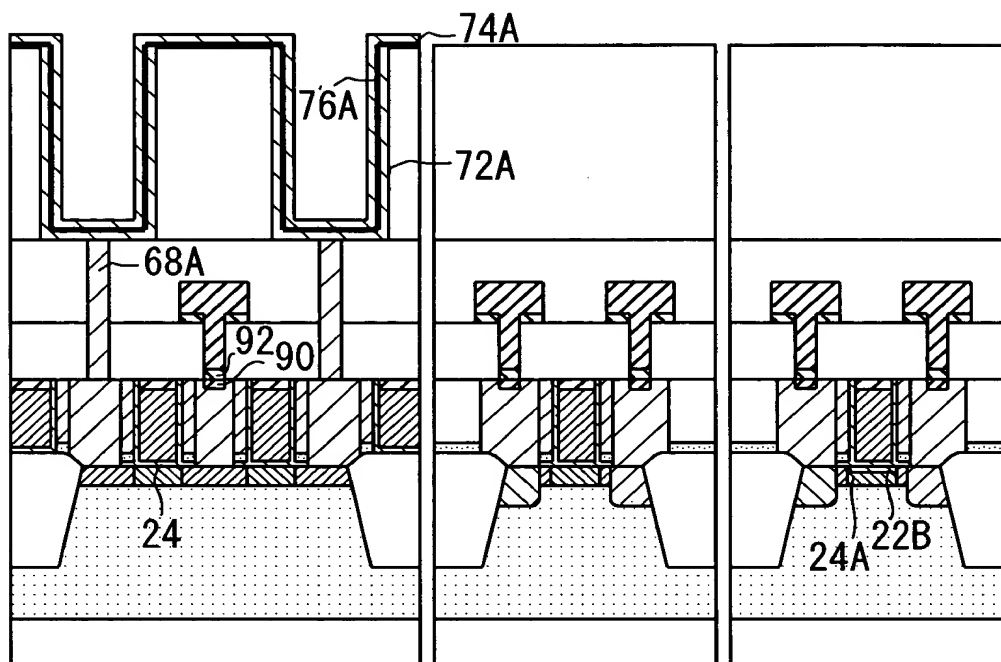


Fig. 25A

Fig. 25B

Fig. 25C

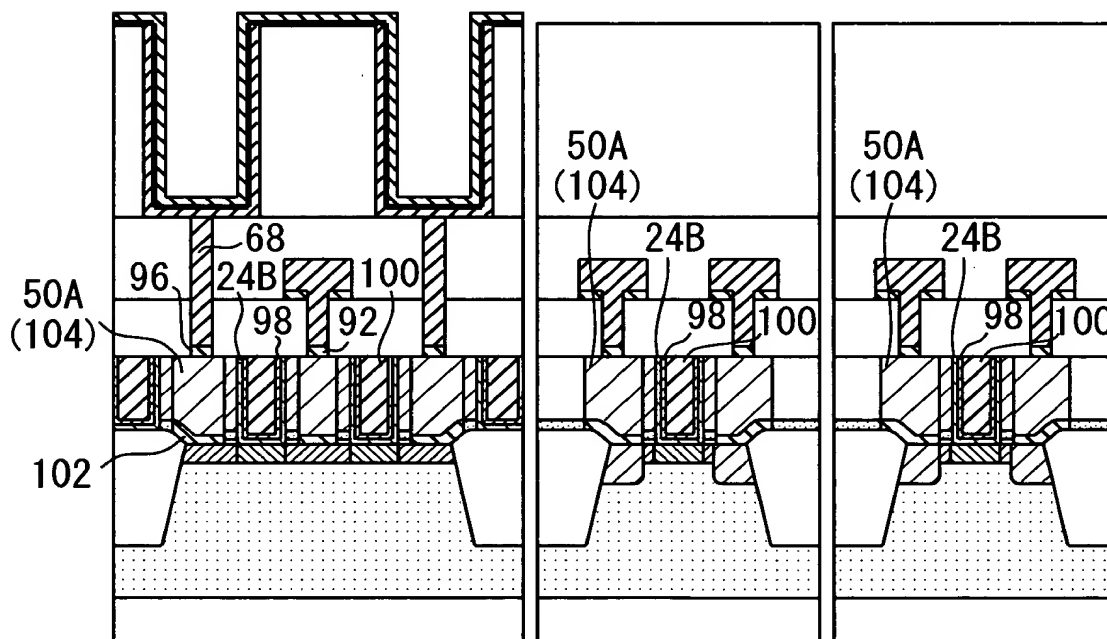
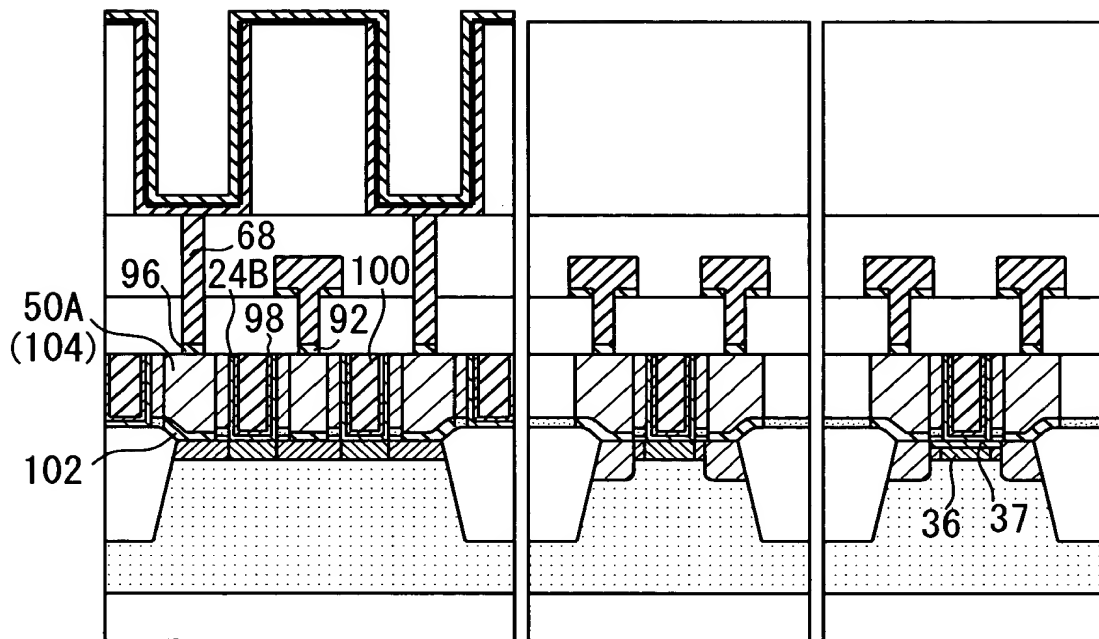


Fig. 26A

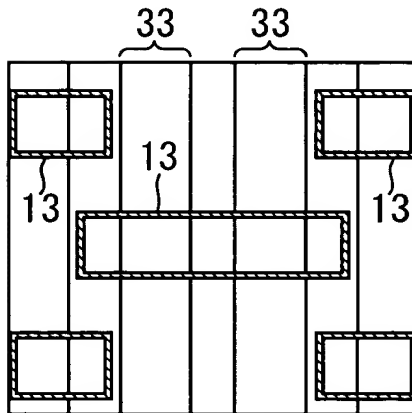
Fig. 26B

Fig. 26C

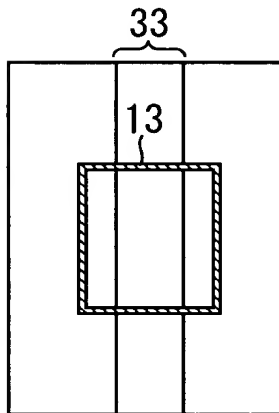




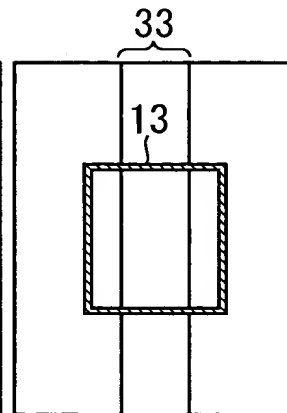
*Fig. 28A*  
PRIOR ART



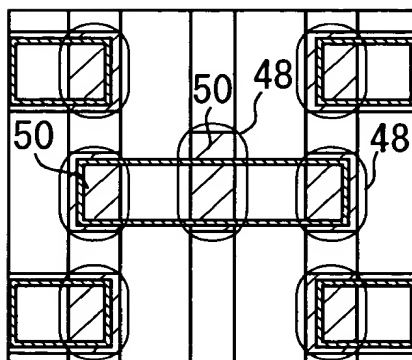
*Fig. 28B*  
PRIOR ART



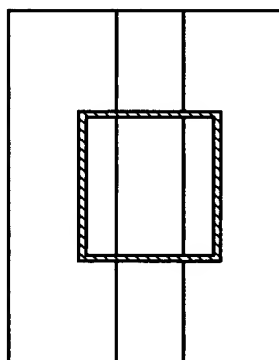
*Fig. 28C*  
PRIOR ART



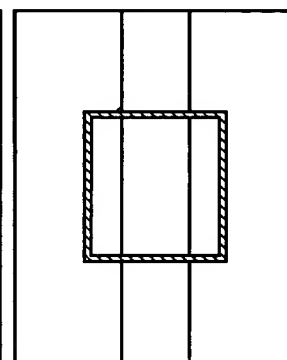
*Fig. 29A*  
PRIOR ART



*Fig. 29B*  
PRIOR ART



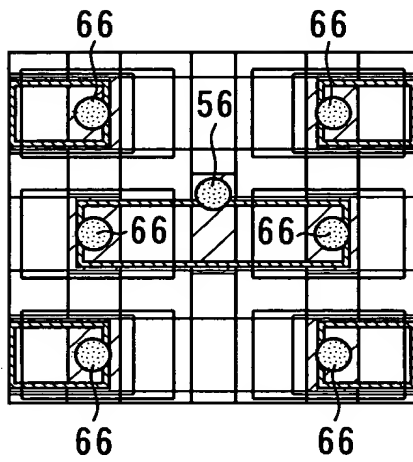
*Fig. 29C*  
PRIOR ART





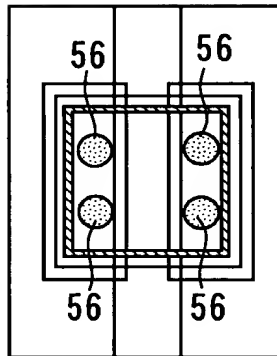
*Fig. 30A*

PRIOR ART



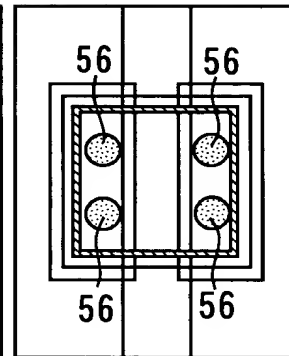
*Fig. 30B*

PRIOR ART



*Fig. 30C*

PRIOR ART



09766846-012301  
FIG. 30A